



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

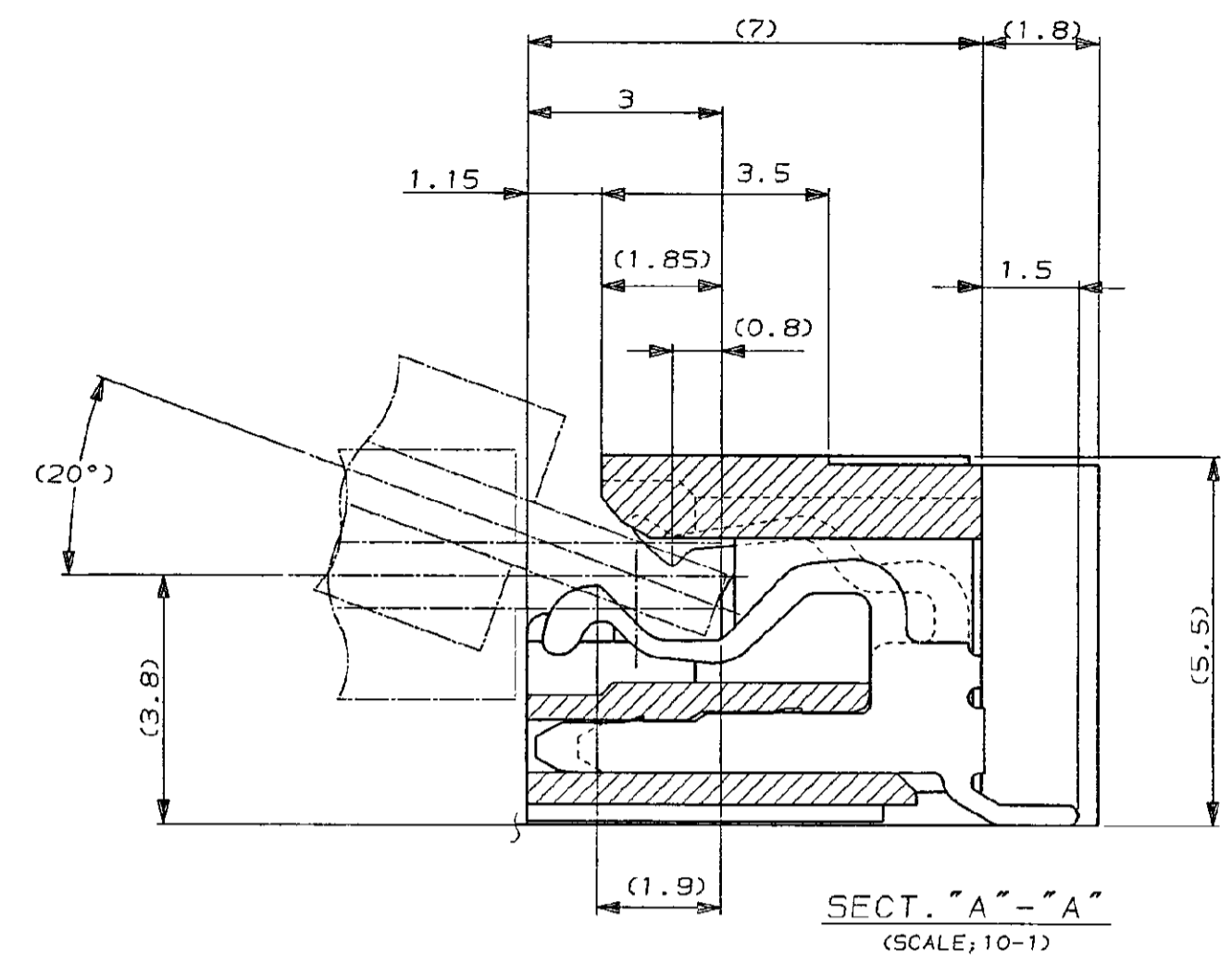
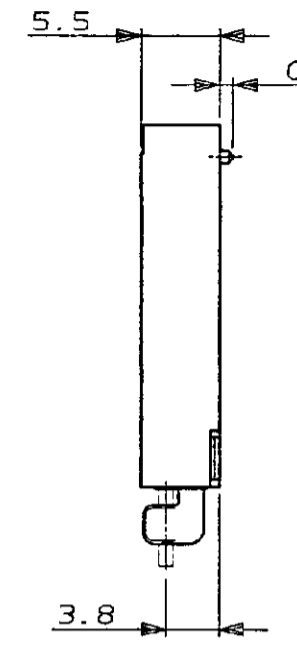
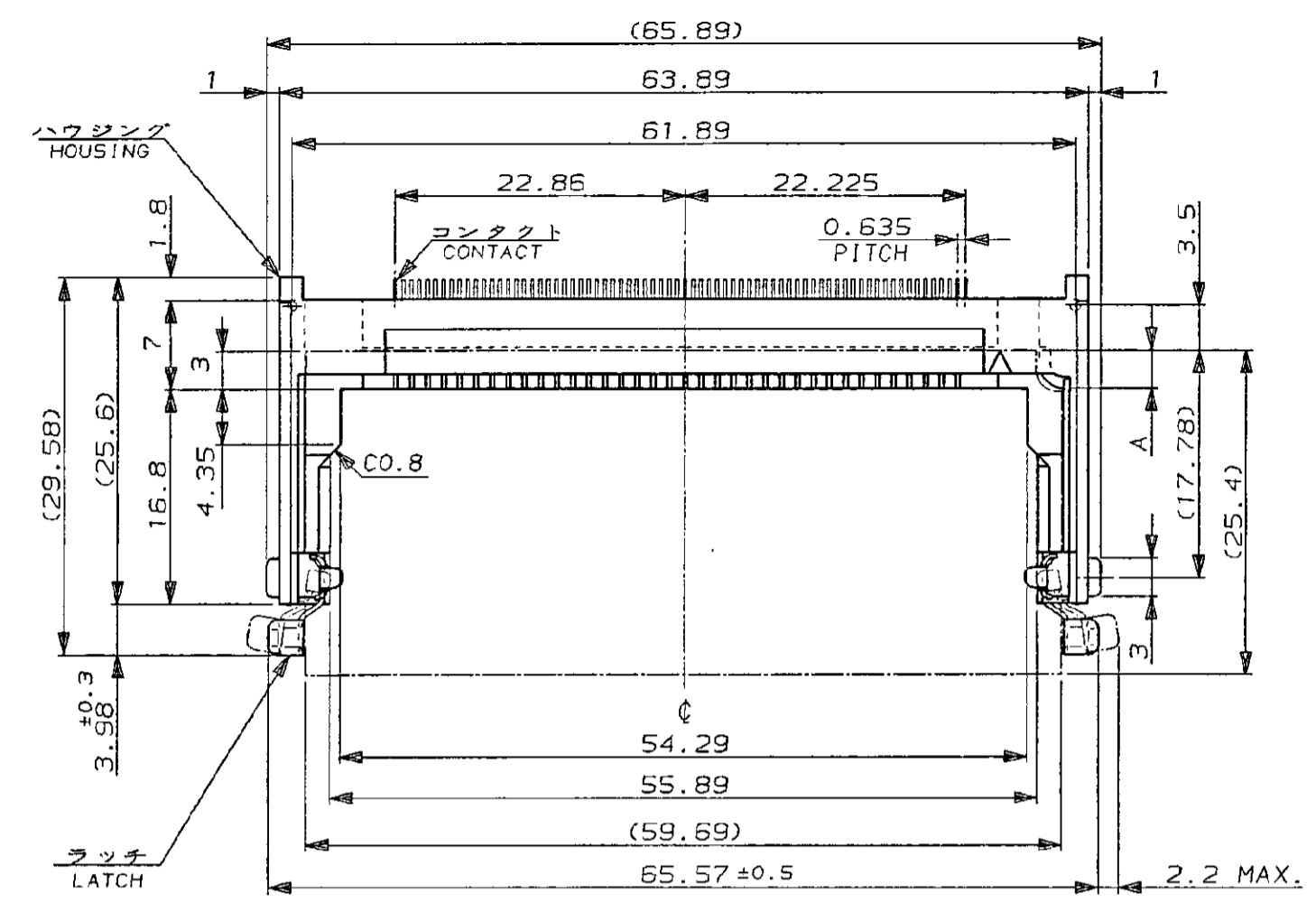
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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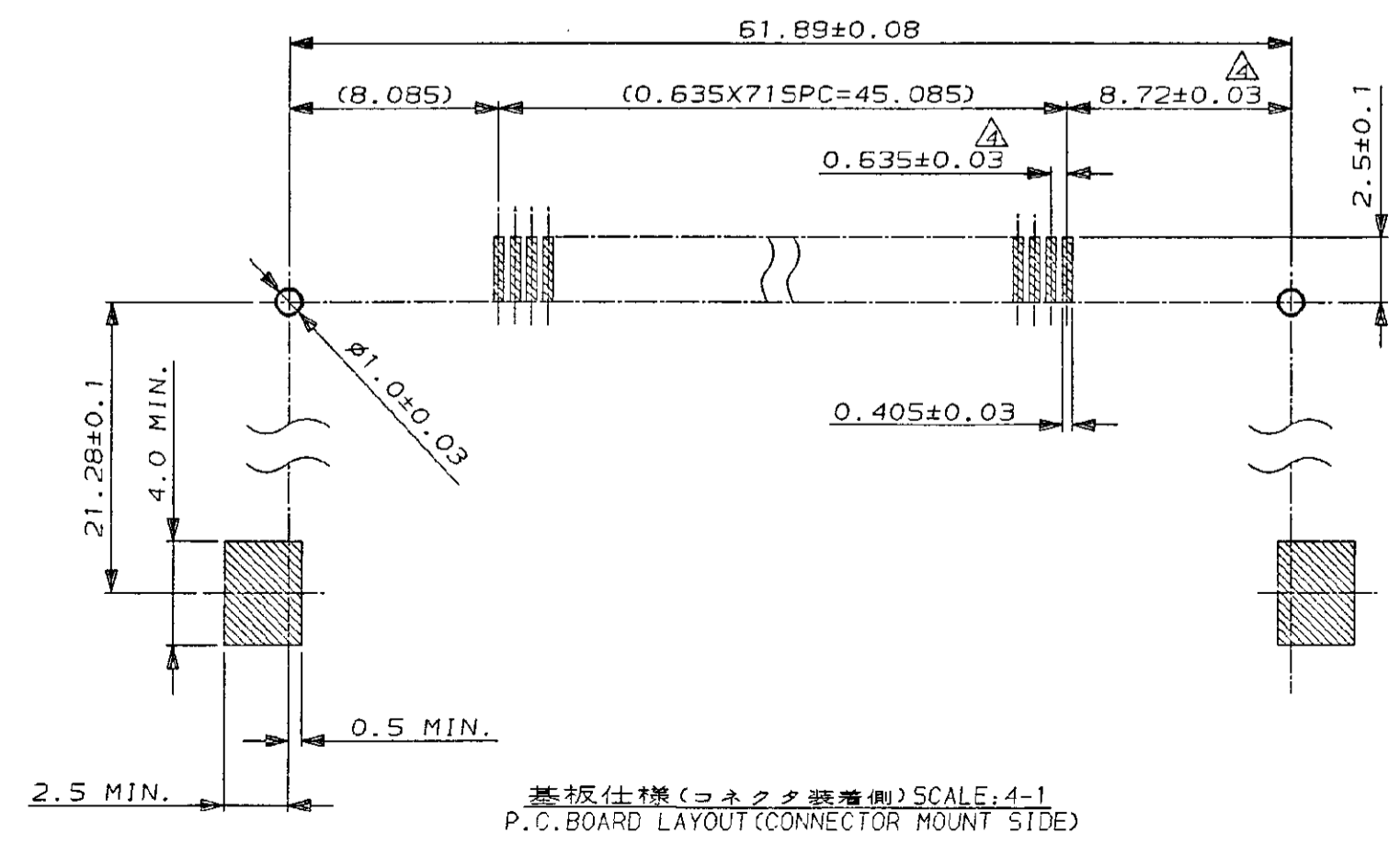
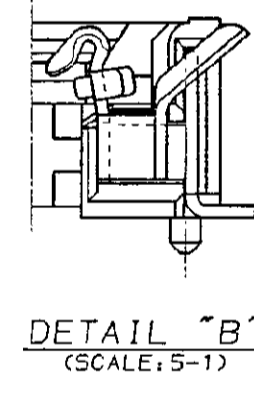
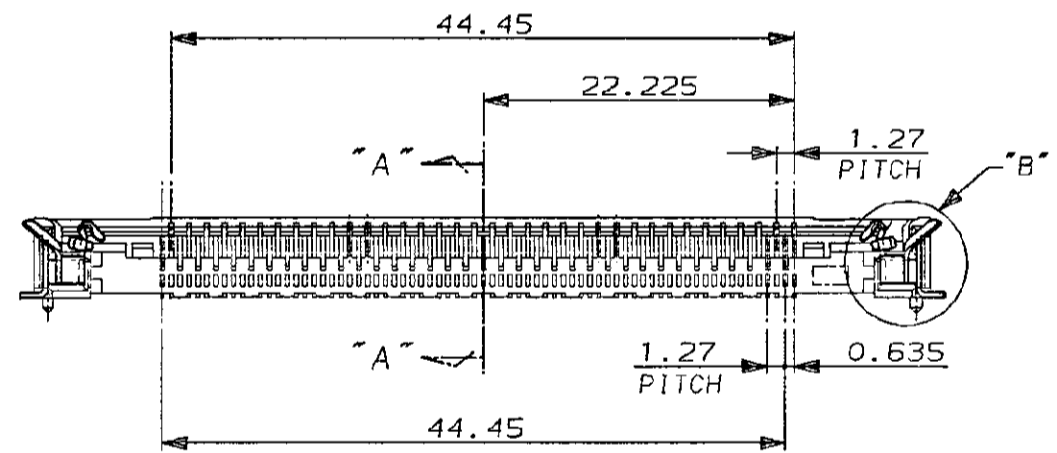
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NUMBER C-177827
METRIC



- NOTES
- MATERIAL & FINISH
HOUSING : GLASS FILLED LCP
CONTACT : COPPER ALLOY
FINISH...SEE NOTES Δ Δ
LATCH : COPPER ALLOY, TIN-LEAD PL.
 - Δ CONTACT PLATING (Au PL. TYPE)
Au(0.3 μ m) PL. AT CONTACT, TIN-LEAD PL. AT TINE OVER Ni PL.
 - Δ CONTACT PLATING (TIN-LEAD PL. TYPE)
TIN-LEAD PL. (2 μ m) OVER Ni PL.
 - Δ TOLERANCE : NON CUMULATIVE.
 - Δ CONTACT PLATING (Au PL. TYPE)
Au(1.27 μ m) PL. AT CONTACT, TIN-LEAD PL. AT TINE OVER Ni PL.
 - Δ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



- 注記
- 材質及び仕上
ハウジング : ガラス入りLCP
コンタクト : 銅合金、仕上...注記 Δ Δ 参照
ラッチ : 銅合金、半田メッキ
 - Δ コンタクトメッキ仕様 (Auメッキ品)
ニッケル下地メッキに接触部金メッキ (0.3 μ m)
ダイナ部半田メッキ
 - Δ コンタクトメッキ仕様 (半田メッキ品)
ニッケル下地メッキに全面半田メッキ (2 μ m)
 - Δ 非累積公差
 - Δ コンタクトメッキ仕様 (Auメッキ品)
ニッケル下地メッキに接触部金メッキ (1.27 μ m)
ダイナ部半田メッキ

NATURAL		2.98	Δ 1.27 μ m Au	2-177827-1
			Δ TIN-LEAD	177827-4
BLACK		6.15	Δ 0.3 μ m Au	177827-3
			Δ TIN-LEAD	177827-2
NATURAL	1.0	2.98	Δ 0.3 μ m Au	177827-1
HOUSING COLOR	C	A	メッキ (接点) PLATING (CONTACT POINT)	PART No.

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D1	REVISED PER - ECO-10-000444	KK	AEG	JAN10	177827-1
D	REVISED (FJ00-1949-95)	S.A	Y.F	30/AUG/94	177827-4
C	REVISED (FJ00-1153-94)	T.Y	Y.F	30/AUG/94	177827-3
B	REVISED (FJ00-0722-94)	T.Y	Y.F	17/JAN/94	177827-2
A	REVISED (FJ00-0070-94)	T.Y	Y.F	26/OCT/93	177827-1
O	RELEASED (FJ00-0176-93)	T.Y	Y.F	26/OCT/93	177827-1
LTR	変更 (REVISION RECORD)	DR	CHK	DATE	

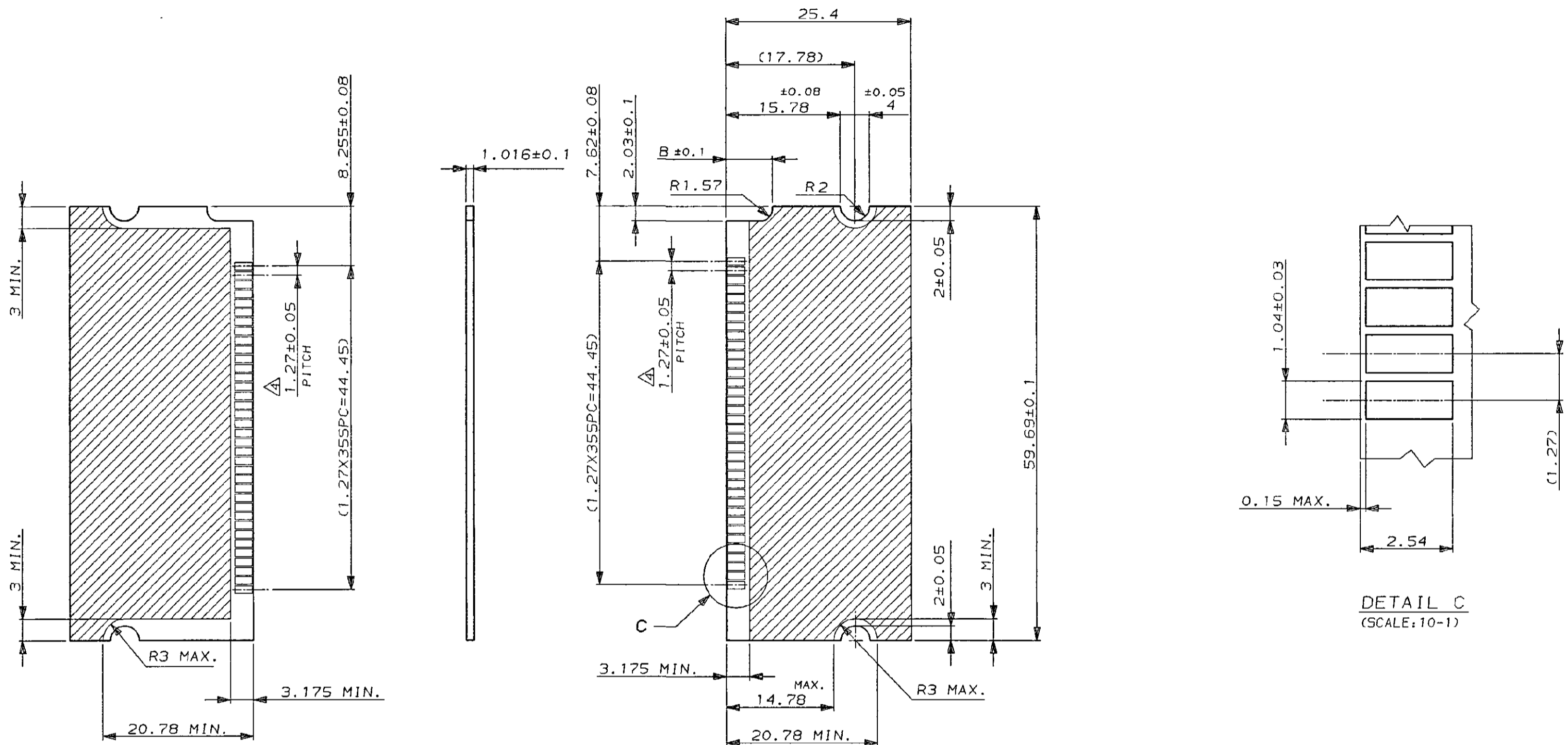
材料 (MATERIAL)	仕上 (FINISH)	一般公差 (GENERAL TOLERANCE)	LOD	番号 (No.)
SEE NOTES	SEE NOTES	10mm: ±0.2 15mm: ±0.25 30mm: ±0.3 公差: ±0.3	C	J
DR. T. YAMADA	DE. T. YAMADA	尺度 (SCALE)	REV.	SHEET
CHK. Y. FUJIIURA	APP. Y. FUJIIURA	2-1	D1	1 OF 2

基板仕様 (コネクタ装着側) SCALE: 4-1
P.C. BOARD LAYOUT (CONNECTOR MOUNT SIDE)

NUMBER
C-177827



METRIC



部品実装領域
COMPONENT AREA

推荐基板 (SMALL OUTLINE SIMM) 寸法
RECOMMENDED DIMENSIONS OF "SMALL OUTLINE SIMM" P.C. BOARD

DETAIL C
(SCALE: 10-1)

6.35	5.0V
3.175	3.3V
B	回路電圧 CIRCUIT VOLTAGE

PRINT DIST
DIMENSIONS IN MM. DO NOT SCALE PRINT

REV. 01/93

SEE SHEET 1

LTR	変更 (REVISION RECORD)	DR	CHK	DATE
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AMP 株式会社
Tokyo, Japan

名称 (NAME)
M III SOCKET

材料 (MATERIAL)	仕上 (FINISH)	一般公差 (GENERAL TOLERANCE)	LOC	番号 (No.)
SEE NOTES	SEE NOTES	10mm ±0.2 100mm ±0.25 300mm ±0.3 角度 ±3°	C J	C-177827
DR. T. YAMADA 26/01/93	DE. T. YAMADA 26/01/93		尺度 (SCALE)	REV. D1
CHK. Y. FUJITURA 26/01/93	APP. Y. FUJITURA 26/01/93		2-1	SHEET 2 OF 2

(CUSTOMER DRAWING) 参考 面